



Part Number:		AS4C128M8D3-12BCN / AS4C128M8D3-12BIN / AS4C128M8D3-12BAN							
Part Weight:		165.518mg							
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	HL-832NX / AUS 308	57.4	E-Glass fabric	65997-17-3	21.00%	12.054	7.28	72825.74022
				Epoxy resin	29690-82-2	21.00%	12.054	7.28	72825.74022
				Fillers	21645-51-2	7.00%	4.018	2.43	24275.24674
				DOPO	35948-25-5	7.00%	4.018	2.43	24275.24674
				Copper	7440-50-8	14.00%	8.036	4.86	48550.49348
				Talc containing no asbestiform fibers	14807-96-6	0.47%	0.269	0.16	1622.973639
				Morpholine derivative	Trade secret	0.47%	0.269	0.16	1622.973639
				Barium sulfate	7727-43-7	5.48%	3.148	1.90	19017.92187
				Silica, amorphous	7631-86-9	0.11%	0.062	0.04	374.5323783
				Dipropylene glycol monomethyl ether	34590-94-8	0.95%	0.544	0.33	3287.561987
				Epoxy resin A	Trade secret	3.46%	1.984	1.20	11985.0361
				Epoxy resin B	85954-11-6	1.07%	0.613	0.37	3703.709074
				Nickel	7440-02-0	15.00%	8.610	5.20	52018.38587
				Gold	7440-57-5	3.00%	1.722	1.04	10403.67717
2	Mold compound	CEL-1802HF	66.06	Epoxy resin-1	Trade secret	5.50%	3.633	2.20	21951.03384
				Epoxy resin-2	Trade secret	2.75%	1.817	1.10	10975.51692
				Phenol Resin	Trade secret	6.50%	4.294	2.59	25942.13091
				Metalhydroxide	Trade secret	5.50%	3.633	2.20	21951.03384
				Carbon black	1333-86-4	0.20%	0.132	0.08	798.2194125
				Silica	60676-86-0	77.55%	51.230	30.95	309509.5772
				Others	Trade secret	2.00%	1.321	0.80	7982.194125
3	Epoxy	6202C	1.033	Polymeric material	Trade secret	20.00%	0.207	0.12	1247.595433
				Epoxy resin	Trade secret	7.50%	0.077	0.05	467.8482876
				Di-ester resin	Trade secret	3.00%	0.031	0.02	187.139315
				Functionalized urethane resin	Trade secret	3.00%	0.031	0.02	187.139315
				Siloxane polymer	Trade secret	20.00%	0.207	0.12	1247.595433
				Mixture of synthetic and fused silica	Trade secret	20.00%	0.207	0.12	1247.595433
				Carbitol acetate	112-15-2	26.50%	0.274	0.17	1653.063949
4	Solder ball	Sn/Ag/Cu	27.526	Tin	7440-31-5	96.50%	26.563	16.05	160482.3572
				Silver	7440-22-4	3.00%	0.826	0.50	4989.088826
				Copper	7440-50-8	0.50%	0.138	0.08	831.5148044
5	Gold wire	Au	0.424	Gold	7440-57-5	99.99%	0.424	0.26	2564.41308
				Others	Trade secret	0.01%	0.000	0.00	0.256466955
6	Die	Chip	13.075	Silicon	7440-21-3	100.00%	13.075	7.90	78995.44703
165.518						600.00%	165.518	100.00	1000000